

Abstract

The invention relates to a cooling device (1) for an electronic component (3), especially for a microprocessor, with a heat sink (7, 9), which can be connected to the electronic component (3) to be cooled, such that the waste heat generated by the electronic component (3) is transferred and transported away via a thermal interface of the electronic component (3) on the heat sink (7, 9). According to the invention, the heat sink (7, 9) comprises a first heat sink part (7), which is formed for connection to the electronic component, and a second heat sink part (9), which is connected detachably to the first heat sink part (7), such that a low heat transfer resistance is given, wherein at least the predominant part of the waste heat is transferred to a coolant via the second heat sink part (9). In addition, the invention relates to a rack for storing several electronic components, such as servers for data-processing systems, wherein at least one electronic component (3) to be cooled is arranged on or in several electronic components. The electronic components to be cooled are each equipped with a cooling device (1) according to the invention, which is formed as cooling devices carrying a flow of a liquid medium.

Principle drawing is Figure 5.